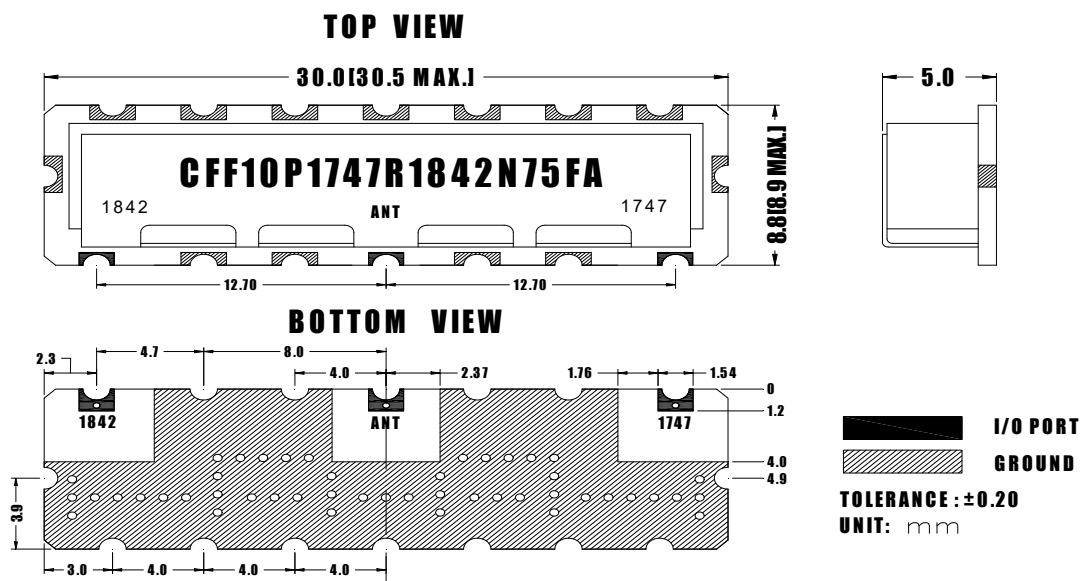


Electrical Specification

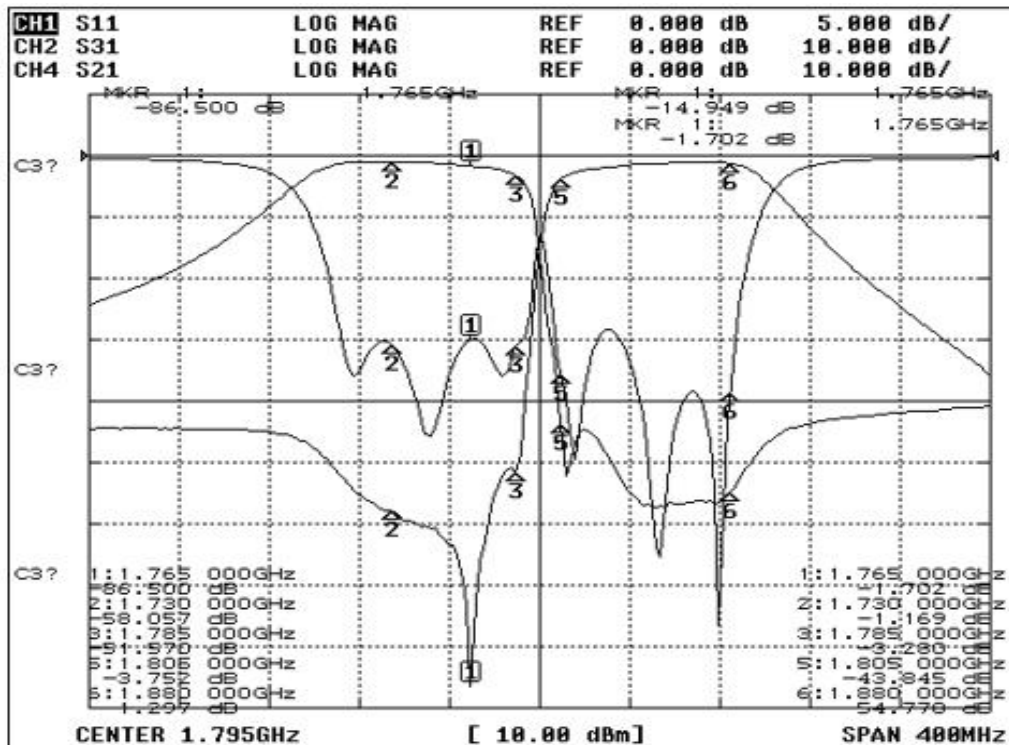
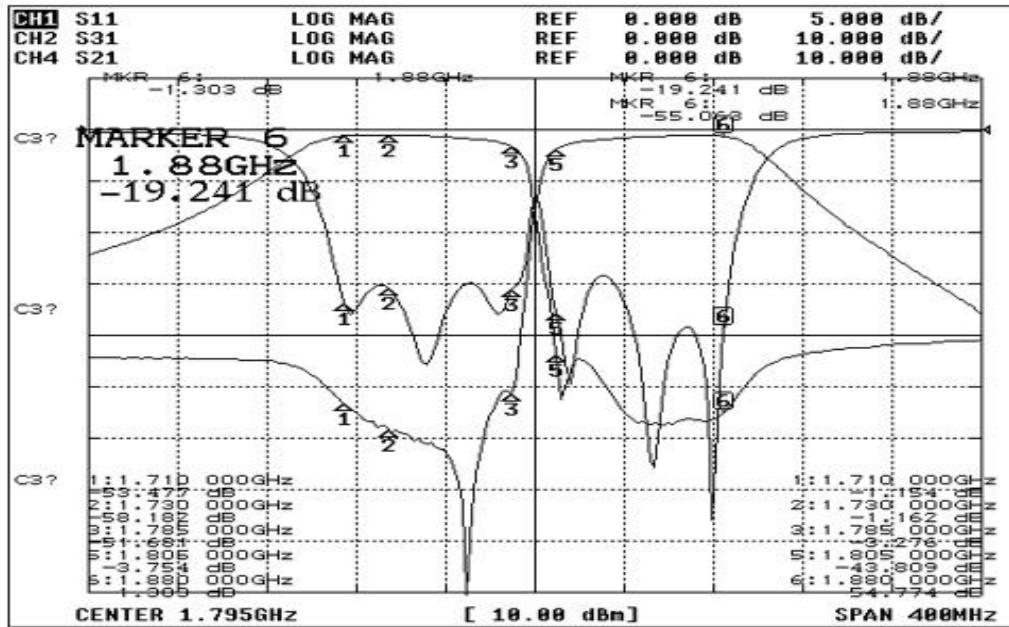
ITEMS	ANT>>LOW	ANT>>High	UNIT
Center Frequency [fo]	1747.5	1842.5	MHz
Bandwidth [BW]	fo ±37.5 [1710~1785]	fo ±37.5 [1805~1880]	MHz
Insertion Loss in BW	2.0dB max @ [ RX:1710~1730 ]	2.0dB max@ [TX:1860~1880]	dB max
	4.0dB max @ [ RX:1765~1785 ]	4.0dB max@ [TX:1805~1825]	dB max
Ripple in BW	2.0dB max @ [ RX:1710~1730 ]	2.0dB max@ [TX:1860~1880]	dB max
	3.5dB max @ [ RX:1765~1785]	4.0dB max@ [TX:1805~1825]	dB max
Return Loss in BW <input checked="" type="checkbox"/> ANT Port	14.0	14.0	dB min
VSW Rin BW <input checked="" type="checkbox"/> ALL Port			max
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	37.0dB min@[1805~ 1880]	40.0dB min@[1805~ 1880]	MHz
	dB min @ fo ± [ ~ ]	dB min @ fo ± [ ~ ]	MHz
	dB min @ fo ± [ ~ ]	dB min @ fo ± [ ~ ]	MHz
	dB min @ fo ± [ ~ ]	dB min @ fo ± [ ~ ]	MHz
Isolations	43.0dB typ. 40dB min@[1710~ 1785]		MHz
	40.0dB typ. 37dB min@[1805~ 1880]		MHz
Input Power	3		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

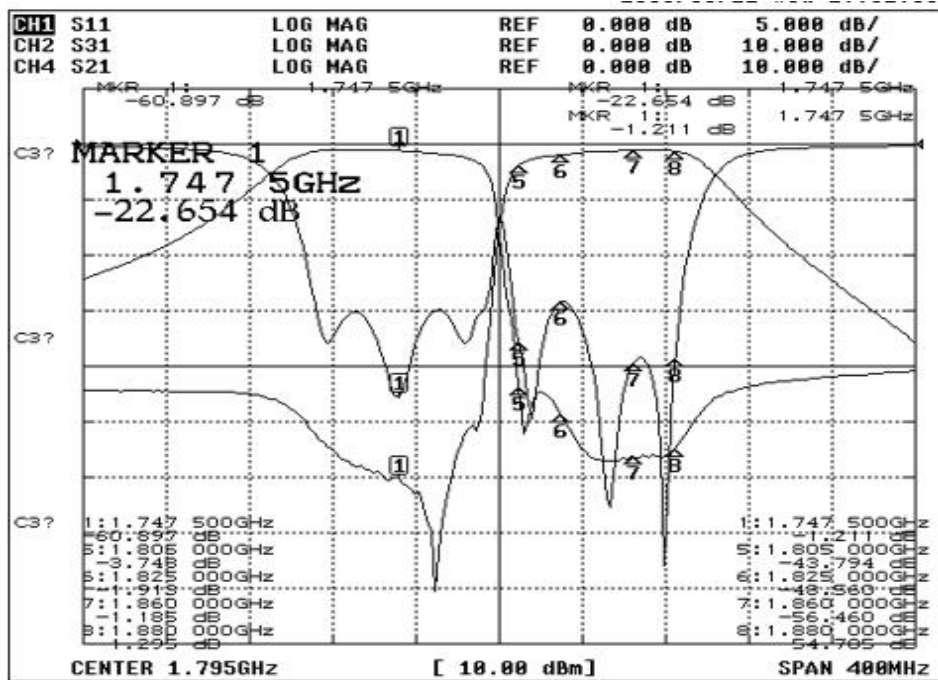
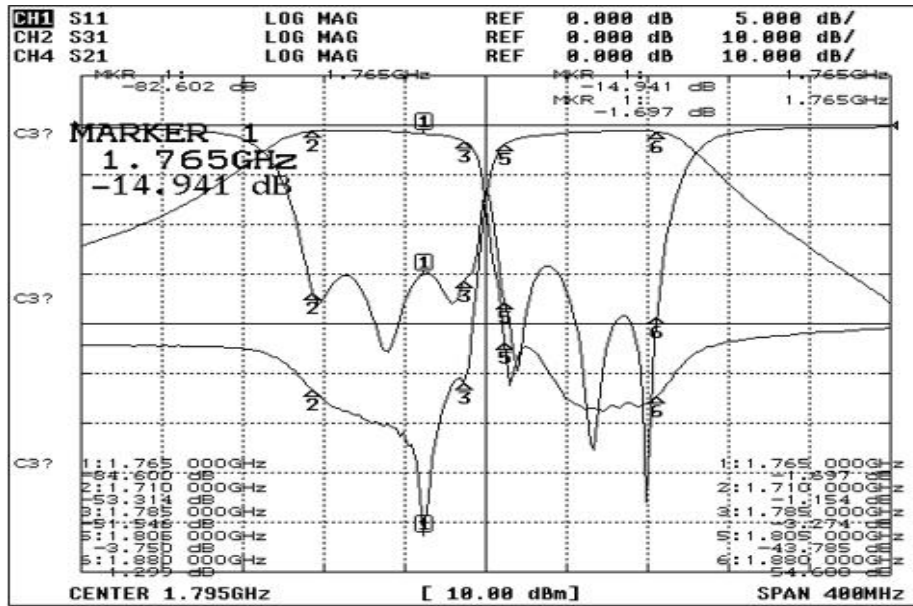
Mechanical Specification

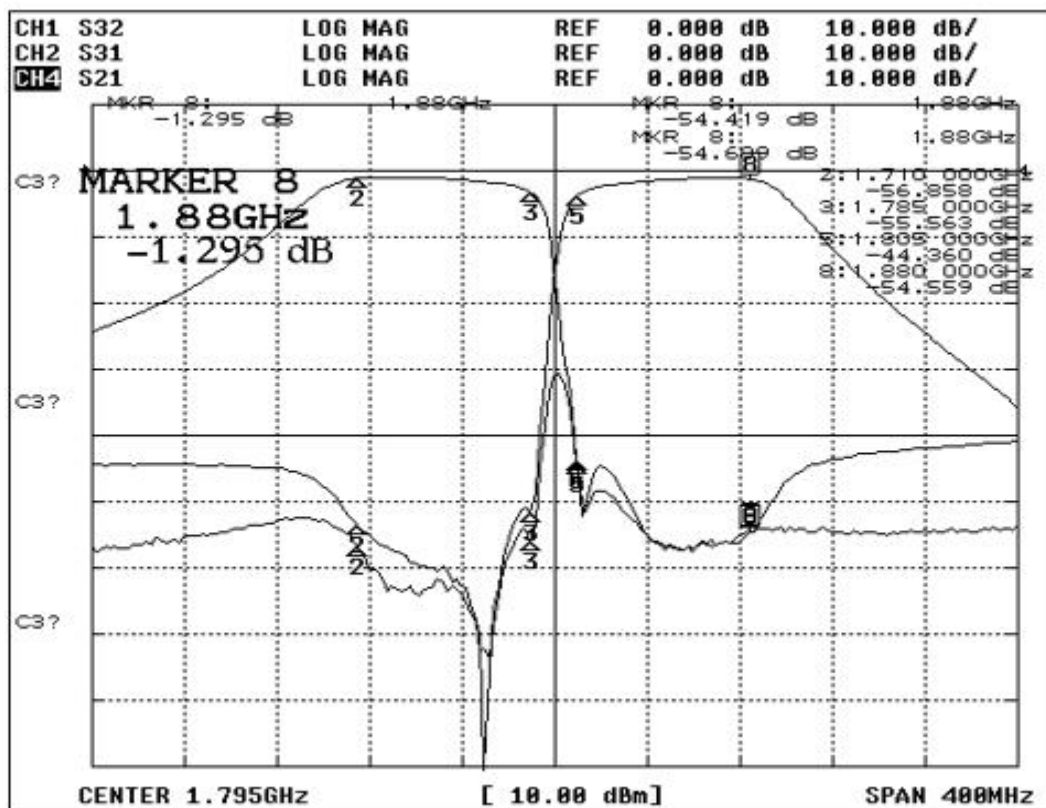
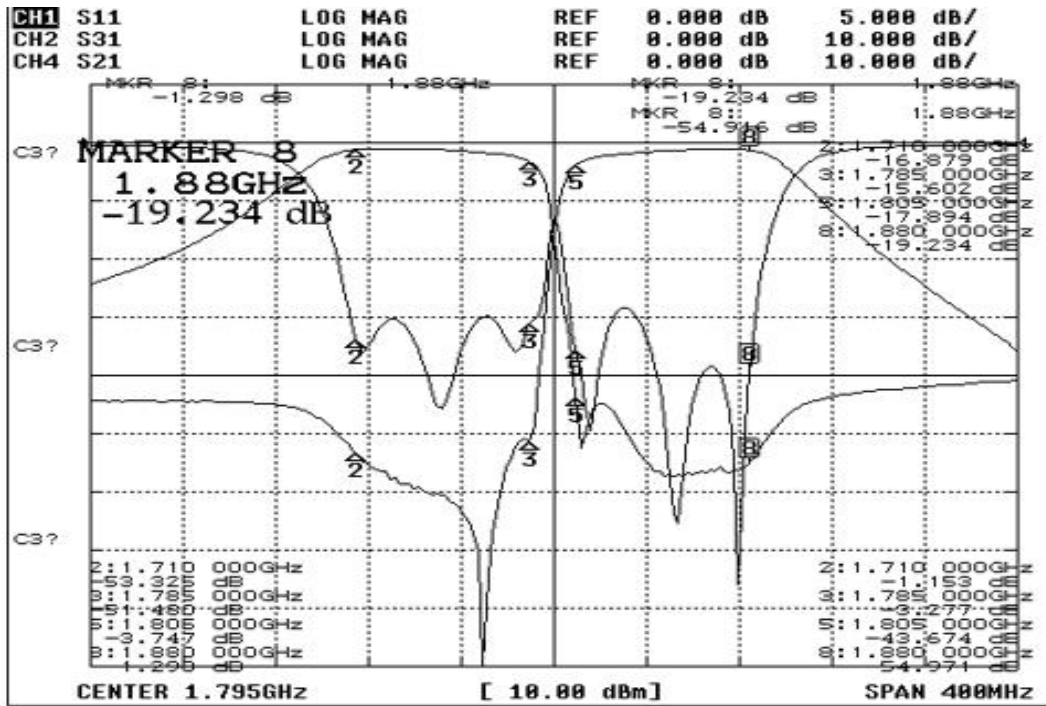




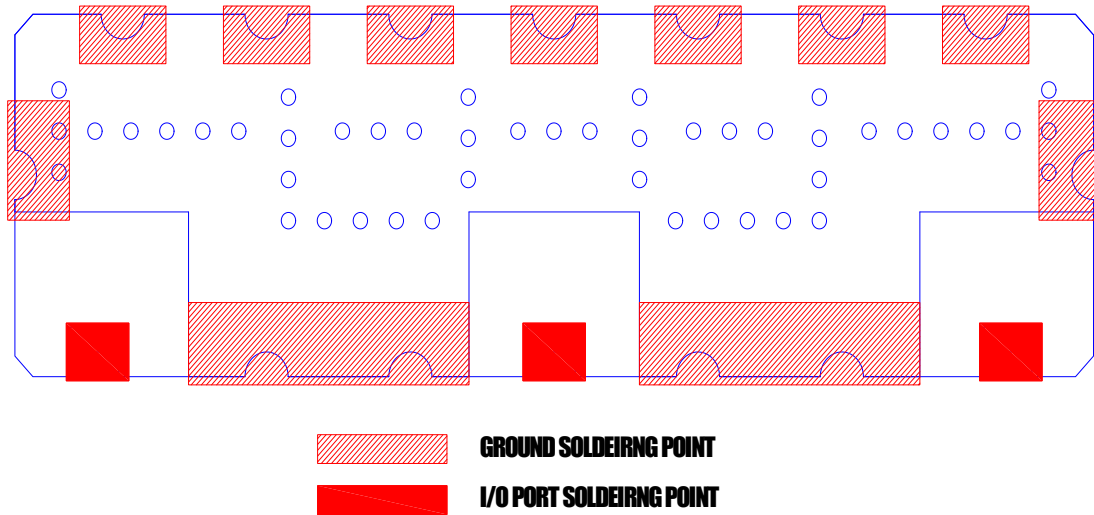
Plot Data



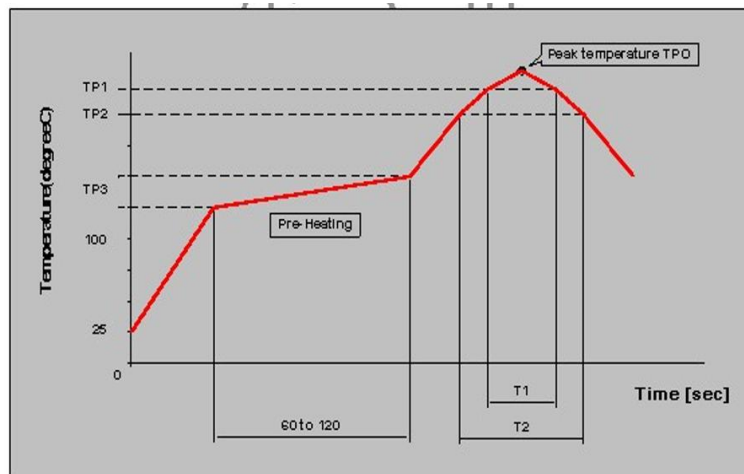




**Recommneded PC Board Pattern**



**Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/-0	240	20	220	70	150 to 180